

Custom Packaging Options for MRO

The aerospace group of Henkel offers several pre-measured packaging options that are especially suitable for maintenance and repair operations. Mixing small quantities of two-component materials is easily accomplished with cartridge kits, pudding cups and E-Z PAK®.

Reduction of Hazardous Waste

With conventional adhesive handling systems, transferring adhesive from one container to another can generate hazardous waste. When adhesive is dispensed using our pre-measured packaging, negligible amounts of adhesive are wasted and may be disposed of in a less costly way, minimizing employee exposure to hazardous materials.

Improved Employee Productivity and Safety

Conventional adhesive systems rely on a technician to measure, transfer, mix, and dispose of resin, catalyst and cured material waste. This process of mixing and preparing adhesives for application diminishes productivity. Pre-measured packaging minimizes time-consuming and costly preparation and disposal activities.

Henkel provides custom packaging services for Hysol® materials. Purchasing your Hysol® custom-packaged material directly or from an authorized Henkel distributor is the best way to assure compliance with OEM specifications and FAA regulations on traceability. Please call with your Hysol® material dispensing or packaging application requirements.

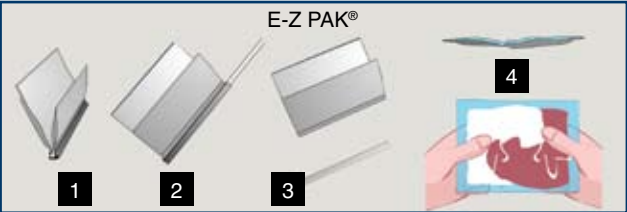
Types of Custom Packaging



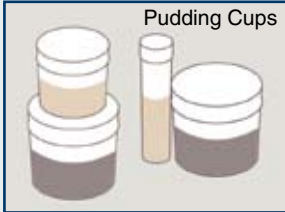
CARTRIDGE KITS: Barrier cartridge kits and injection cartridge kits are disposable plastic cartridges capable of mixing two-component materials prior to dispensing. They are available in 1 oz. to 10 oz. sizes.



DUAL CARTRIDGE/STATIC MIXER KIT: Dual cartridge/static mixer kits store two-component materials, which can be mixed during the dispensing of the product through a static mix nozzle. They are available in 50 ml to 1500 ml sizes.



E-Z PAK®: E-Z PAK® provides a high integrity barrier pouch divided by an easily removable clip. The clip separates two compartments, which can hold almost any two-part adhesive paste.



PUDDING CUPS: Pudding cups offer the convenience of hand mixing with the assurance of correct mix ratios. They are available in a variety of fill sizes designed to fit your processing needs.



Henkel – Your worldwide partner

NORTH AMERICA

Henkel Corporation

Aerospace
P. O. Box 312
2850 Willow Pass Road
Bay Point, CA 94565
USA
Tel: 925.458.8000
Fax: 925.458.8030

Henkel Corporation

Aerospace
32100 Stephenson Hwy.
Madison Heights, MI 48071
USA
Tel: 866.332.7024
Fax: 248.585.2896

Henkel Canada Corporation

Aerospace
2225 Meadowpine Blvd.
Mississauga, Ontario
Canada L5N 7P2
Tel: 905.814.6511
Fax: 905.814.6522



Henkel Corporation

For additional information:
866.332.7024

visit www.henkelna.com/aerospace

EUROPE

Henkel France

Aerospace
82, rue de Maubec
31300 Toulouse
France
Tel: +33.5.34.36.40.60
Fax: +33.5.34.36.40.69

Henkel France

Aerospace
Buioparc-Batiment B,
3 Allée Emile Reynaud
F-77200 Torcy
Tel: +33.1.6017.0202
Fax: +33.1.6017.3291

Henkel Netherlands

Aerospace
Henkel Nederland B.V.
Brugwal 11
3432 NZ Nieuwegein
The Netherlands
Tel: +31.30.6073.911
Fax: +31.30.6054.457

Henkel Oberflächentechnik GmbH - Germany

Henkelstraße 67
D-40589 Düsseldorf
Tel: +49.211.797.0
Fax: +49.211.798.0

Henkel Central Eastern Europe GmbH – Austria

Erdbergstraße 29
A-1030 Wien
Tel: +43.1.711.040
Fax: +43.1.71104.2534

ASIA

Henkel Singapore Pte. Ltd.

19 Jurong Port Road
Singapore 619093
Tel: +65.6266.0100
Fax: +65.6266.1161

Henkel Asia-Pacific & China Headquarters

No.928 Zhang Heng Road
Zhangjiang Hi-Tech Park, Pudong
Shanghai 201203
P. R. China
Tel: +86.21.2891.8000
Fax: +86.21.6100.6059

Approvals

These products are approved for use in Industry Standard specifications. For more specific approvals and applications, please check the applicable qualified product list or contact your local Henkel technical representative.

PRODUCT	PACKAGE AVAILABILITY												CHARACTERISTICS						APPLICATION	DESCRIPTION
	Pints	Quarts	Gallons	25 Gram EZ Pak®	50 Gram EZ Pak®	2.5 Oz. Cartridge Kits	6 Oz. Cartridge Kits	25 Gram Pudding Cup	50 Gram Pudding Cup	50 ML Dual Cartridge Kits	200 ML Dual Cartridge Kits	400 ML Dual Cartridge Kits	Mix Ratio Weight (Part A : Part B)	Mixed Viscosity (Pose)	Cure Temperature	Cure Time	Storage Temperature	Pot Life		
Hysol® EA 934NA™	•	•	•		•	•	•	•	•				100:33	800	77°F (25°C) 200°F (93°C)	5-7 days 1 hour	40°F (4°C)	40 mins/ 1 lb. (0.5 kg)	Room temperature cure, gap filler, 300°F/149°C performance potting material, develops strength rapidly	Ideal for potting, filling, fairing & shim applications
Hysol® EA 956™	•	•	•	•	•			•	•				100:58	170	77°F (25°C) 200°F (93°C)	5-7 days 1 hour	40°F (4°C)	30 mins/ 1 lb. (0.5 kg)	Low viscosity, room temperature cure, ideal for repair	Very low viscosity, cures at room temperature, maintains strength at high temperatures, ideal for wet lay-up repair
Hysol® EA 960F™		•	•	•				•	•				100:50	—	77°F (25°C) 160°F (71°F)	24 hours 1 hour	77°F (25°C)	30 mins/ 0.25 lb. (0.1 kg)	Rapid cure, color change when mixed, good filler, sandable & paintable, smoothing & fairing compound	Fast-set fairing and smoothing compound for exterior aircraft surfaces; color changes when fully mixed, sandable after six hours
Hysol® EA 9150™ Resin			•										100:88	25	250°F (121°C)	1 hour	77°F (25°C)	480 mins/ 1 lb. (0.5 kg)	Low viscosity RTM resin, long pot life, toughness, room temperature storage, flexibility, 250°F/121°C service temperature	Low viscosity, toughened system formulated for resin transfer molding
Hysol® EA 9309.3NA™		•	•	•	•		•		•				100:22	128	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	77°F (25°C)	35 mins/ 1 lb. (0.5 kg)	High shear & peel strength, bondline thickness controlled structural repair & composite bonding adhesive	Toughened adhesive with excellent peel strength that contains glass beads for bond line control
Hysol® EA 9313™		•											100:25	12	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	77°F (25°C)	60 mins/ 1 lb. (0.5 kg)	High peel strength, room temperature cure, pourable low viscosity, structural repair adhesive	Very low viscosity injectable adhesive yielding tough, flexible bonds
Hysol® EA 9320NA™		•	•	•		•	•						100:19	4000	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	77°F (25°C)	25 mins/ 0.5 lb. (0.25 kg)	High peel, room temperature cure, good elevated temperature strength, general bonding adhesive	High shear and high peel adhesive system with room temperature cure
Hysol® EA 9321™		•	•	•		•	•	•	•	•			100:50	—	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	40°F (4°C)	40 mins/ 1 lb. (0.5 kg)	Two-component system, room temperature cure, good elevated temperature strength, potting & structural repair adhesive	Thixotropic adhesive that yields tough, durable bonds over a wide temperature range
Hysol® EA 9323™		•	•		•	•	•						100:45	150	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	40°F (4°C)	30 mins/ 1 lb. (0.5 kg)	Two-component system, high temperature strength, unfilled, structural repair adhesive	Easy mix adhesive with high peel strength and excellent environmental durability
Hysol® EA 9330™		•	•	•			•		•				100:33	—	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	77°F (25°C)	60 mins/ 0.25 lb. (0.1 kg)	Two-component system, tolerant of bondline thickness variations, room temperature cure, high peel strength excellent environmental resistance, structural repair & composite bonding adhesive	Non-slump thixotropic adhesive with high peel strength & excellent environmental durability
Hysol® EA 9330.3™		•											100:33	—	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	77°F (25°C)	60 mins/ 0.25 lb. (0.1 kg)	Two-component system, low slump, room temperature cure, easy mix, high peel strength, structural repair & composite bonding adhesive	Moderate viscosity, one-component, high peel and shear strength, outstanding hot/wet properties
Hysol® EA 9346.5™		•											—	3500	250°F (121°C)	1 hour	40°F (4°C)	14 days/ 1 lb. (0.5 kg)	Low viscosity, low moisture absorption, aluminum & composite bonding adhesives	Bonds a variety of substrates with excellent peel and shear strength; improvement over Hysol® EA 9309NA™ series adhesives
Hysol® EA 9359.3™		•								•	•	•	100:44	—	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	77°F (25°C)	40 mins/ 1 lb. (0.5 kg)	Easy mixing, good environmental resistance, non-sag, structural repair & composite bonding adhesive	Structural adhesive, exhibits excellent peel strength, and tensile lap shear strength to 250°F/121°C
Hysol® EA 9360™		•	•	•						•	•		100:43	1200	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	77°F (25°C)	40 mins/ 0.5 lb. (0.25 kg)	High peel strength, excellent static stress durability, liquid shim adhesive	Fast-set, tough with handling strength after two hours, exhibits good hot/wet properties
Hysol® EA 9371™		•	•							•			100:62	700	77°F (25°C) 180°F (82°C)	24 hours 1 hour	40°F (4°C)	18 mins/ 0.25 lb. (0.1 kg)	Fast thin film set time, no mercaptans, good hot/wet properties, handling strength within two hours, room temperature cure, structural repair & composite bonding adhesive	Moldable plastic shim, excellent micro-cracking resistance under thermal cycling. and high compressive strength
Hysol® EA 9377™		•		•		•	•		•				100:19	—	77°F (25°C) 180°F (82°C)	5-7 days 1 hour	40°F (4°C)	60 mins/ 0.25 lb. (0.1 kg)	Resistant to micro-cracking under 2,000 thermal cycles, capable of minimum 5 mil shim thickness, liquid shim adhesive	Cures at lower temperature, while offering the strength, toughness and high temperature resistance of heat-curing film adhesives , with greater flexibility and ease of use
Hysol® EA 9380™		•										•	100:55	1600	160°F (70°C)	4 hours	40°F (4°C)	180 mins/ 1 lb. (0.5 kg)	Low temperature curing, two-part adhesive meter mixable, prebond humidity resistant, structural repair & composite bonding adhesive	Low viscosity system for high temperature wet lay-up composite repair, qualified to BMS 8-301
Hysol® EA 9390™		•	•		•		•	•					100:56	140	200°F (93°C)	3.5 hours	40°F (4°C)	120 mins/ 0.5 lb. (0.25 kg)	Wet lay-up resin for graphite or glass composite repairs	Two-component epoxy adhesive designed for composite repair, great wetting, high-shear modulus and good hot/wet properties
Hysol® EA 9394™	•	•	•	•	•	•	•		•	•	•	•	100:17	1600	77°F (25°C) 150°F (66°C)	5-7 days 1 hour	77°F (25°C)	100 mins/ 1 lb. (0.5 kg)	Room temperature cure, outstanding mechanical properties, long pot life, low toxic, potting, liquid shim & structural repair adhesive	Thixotropic adhesive with structural properties to 350°F/177°C
Hysol® EA 9394.2™	•	•											100:27	1600	77°F (25°C) 200°F (93°C)	24 hours 1 hour	77°F (25°C)	15 mins/ 0.25 lb. (0.1 kg)	Fast set time, good gap filling, potting, liquid shim & structural repair adhesive	Fast cure adhesive for liquid shim and potting, handling strength within six to eight hours
Hysol® EA 9394™/C-2		•		•			•						100:20	—	200°F (93°C)	1 hour	77°F (25°C)	480 mins/ 1 lb. (0.5 kg)	Excellent strength above 400°F/204°C, long pot life, structural repair adhesive	Elevated cure, thixotropic adhesive with structural properties to 450°F/232°C
Hysol® EA 9395™		•	•	•			•						100:17	2000	77°F (25°C) 150°F (66°C)	5-7 days 1 hour	77°F (25°C)	100 mins/ 1 lb. (0.5 kg)	Non-metallic filled, excellent mechanical properties, potting & structural repair adhesive	Two-part, non-metallic filled version of Hysol® EA 9394™
Hysol® EA 9396™	•	•	•	•	•	•	•	•	•				100:30	35	77°F (25°C) 150°F (66°C)	5-7 days 1 hour	77°F (25°C)	75 mins/ 1 lb. (0.5 kg)	Low viscosity, room temperature cure, high strength at low & high temperature, wet lay-up resin and composite bonding adhesive	Two-part, low viscosity, unfilled version of Hysol® EA 9394™, qualified to BMS 8-301
Hysol® EA 9396™/C-2		•											100:36	—	200°F (93°C)	1 hour	77°F (25°C)	480 mins/ 0.25 lb. (0.1 kg)	Low viscosity, long worklife, neat lay-up resin	Two-part, elevated cure, unfilled, low viscosity adhesive with structural properties to 400°F/204°C
Hysol® EA 9396.6™ MD			•				•						100:31	—	77°F (25°C) 150°F (66°C)	5-7 days 1 hour	40°F (4°C)	120 mins/ 1 lb. (0.5 kg)	Good high temperature properties, low density, potting & edge fill adhesive	77°F/25°C cure syntactic, with excellent high temperature properties and density of 37 pcf (0.6 g/cc)
Hysol® EA 9815™							•						—	3500	250°F (121°C)	1 hour	0°F (-18°C)	14 days/ 1 lb. (0.5 kg)	25% closed cell expansion, low moisture absorption, potting & composite bonding adhesive	Pumpable, one-component, high peel and high-shear strength when bonding to aluminum and composite substrates

